



Docket No.: M4065.0361/P361
(PATENT)

#17/12
3/3/03
Adm H

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Whonchee Lee, et al.

Application No.: 09/653,411

Group Art Unit: 2815

Filed: August 31, 2000

Examiner: Joseph H. Nguyen

For: ELECTRO-MECHANICAL POLISHING
OF PLATINUM CONTAINER
STRUCTURE

AMENDMENT

BOX: Non-Fee Amendment

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated November 25, 2002, please amend the
above-captioned application as follows:

IN THE CLAIMS:

Please rewrite claims 39, 43, and 48-51 as follows:

39. (Twice Amended) A semiconductor device comprising:

a substrate; and

at least one electro-mechanically polished metal layer formed over said
substrate, said electro-mechanically polished metal layer containing no hardening
additive.

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